AUTOMOTIVE

RoHS COMPLIANT

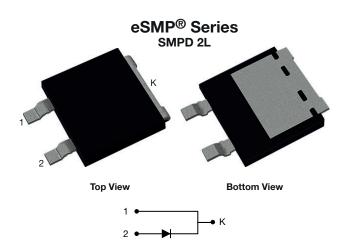
HALOGEN

FREE



Vishay General Semiconductor

Surface-Mount ESD Capability Rectifiers



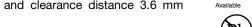
LINKS TO ADDITIONAL RESOURCES

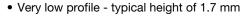


PRIMARY CHARACTERISTICS				
I _{F(AV)}	10 A			
V _{RRM}	400 V, 600 V			
I _{FSM}	110 A			
V_F at $I_F = 10 \text{ A } (T_J = 125 \text{ °C})$	0.96 V			
I _R	15 μA			
T _J max.	175 °C			
Package	SMPD 2L			
Circuit configuration	Single			

FEATURES

• Creepage and clearance distance 3.6 mm minimum





- · Ideal for automated placement
- · Oxide planar chip junction
- Low forward voltage drop
- ESD capability
- AEC-Q101 qualified available
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both consumer and automotive on board charger (OBC) applications.

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and industry grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	SE10DTG	SE10DTJ	UNIT			
Device marking code		SE10DTG	SE10DTJ	V			
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	V			
Maximum DC forward current	I _F ⁽¹⁾	10		^			
	I _F ⁽²⁾	2.9		_ A			
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM}	11	А				
Operating junction and storage temperature range	T _J , T _{STG}	-55 to	°C				

Notes

- (1) With heatsink
- (2) Free air, mounted on recommended copper pad area



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 5 A	- T _J = 25 °C	V _F ⁽¹⁾	0.95	-	V
	I _F = 10 A			1.04	1.15	
	I _F = 5 A	- T _J = 125 °C		0.85	=	
	I _F = 10 A			0.96	1.10	
Reverse current	Rated V _R	T _J = 25 °C	I _R ⁽²⁾	=	15	μА
	naieu v _R	T _J = 125 °C		22	150	
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}	3000	-	ns
Typical junction capacitance	4.0 V, 1 MHz		CJ	67	=	pF

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)					
PARAMETER SYMBOL TYP. MAX. UN					
Thermal resistance	R _{0JA} (1)(2)	60	75	°C/W	
THEITIGI TESISLATICE	R _{0JM} (3)	1.8	2.2		

- $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS ($T_A = 25~^{\circ}\text{C}$ unless otherwise noted)						
STANDARD TEST TYPE TEST CONDITIONS SYMBOL CLASS VALUE						
AEC-Q101-001	Human body model (contact mode)	C = 100 pF, R = 1.5 kΩ	V _C	H3B	> 8 kV	

ORDERING INFORMATION (Example)						
PREFERRED P/N UNIT WEIGHT (g) PREFERRED PACKAGE CODE BASE QUANTITY DELIVERY MODE						
SE10DTJ-M3/I	0.52	I	2000 / reel	13" diameter plastic tape and reel		
SE10DTJHM3/I (1)	0.52	I	2000 / reel	13" diameter plastic tape and reel		

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

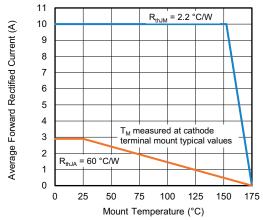
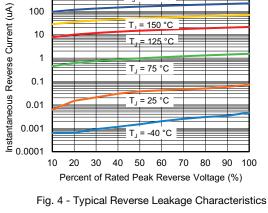


Fig. 1 - Forward Current Derating Curve



T_{.1} = 175 °C

1000

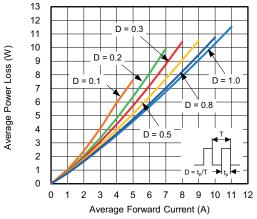


Fig. 2 - Forward Power Loss Characteristics

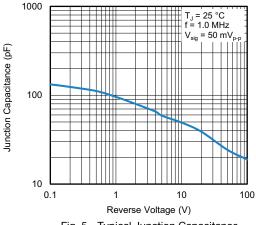


Fig. 5 - Typical Junction Capacitance

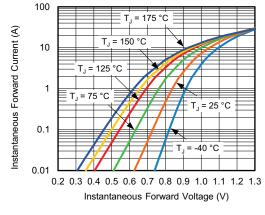


Fig. 3 - Typical Instantaneous Forward Characteristics

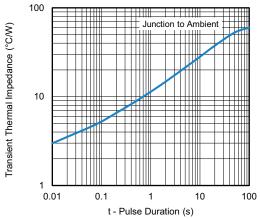
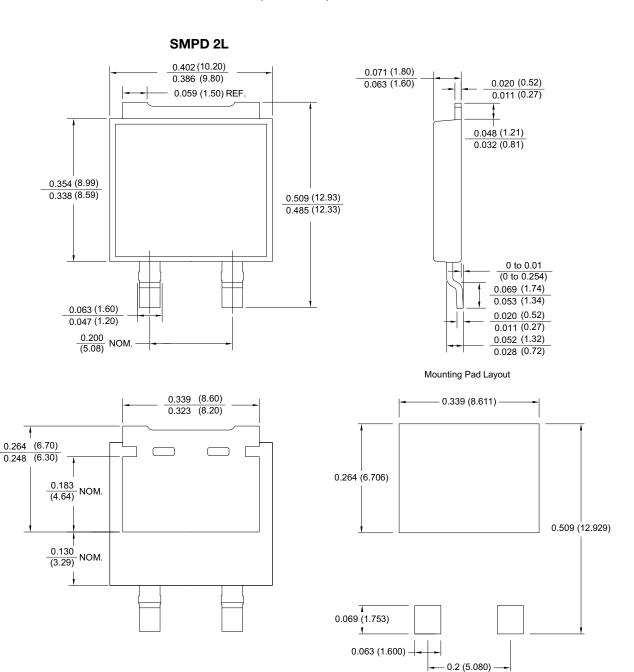


Fig. 6 - Typical Transient Thermal Impedance



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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)



Note

• The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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